



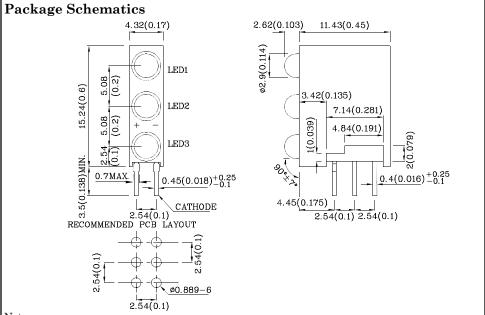
T-1 (3mm) TRI-LEVEL LED INDICATOR

Features

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- \bullet Reliable & robust
- Custom color combinations available
- RoHS Compliant







Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		UR (GaAsP/GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	160	mA	
Power Dissipation	P_{D}	75	mW	
Operating Temperature	T _A -40 ~ +85		°C	
Storage Temperature	Tstg	-40 ~ +85	C	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

Operating Characteristics (T_A =25°C)		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) $(I_F=10 \text{mA})$	V_{F}	1.9	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λP	627*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λD	617*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	45	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

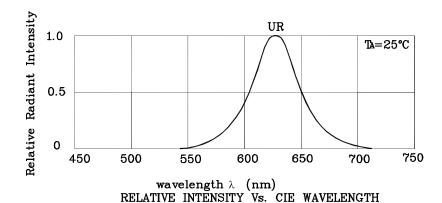
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =10mA) mcd		Wavelength CIE127-2007* nm λΡ	Viewing Angle 2θ 1/2
				min.	typ.		
XPZ3LUR147D	Red	GaAsP/GaP	Red Diffused	12 6*	24 11*	627*	40°

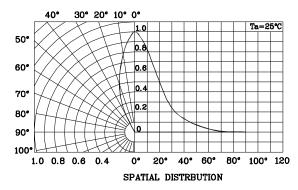
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Dec 28,2013 XDSA7874 V6-X Layout: Maggie L.

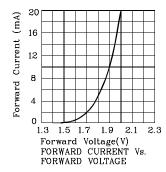


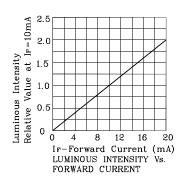


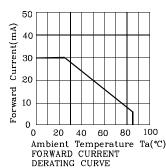


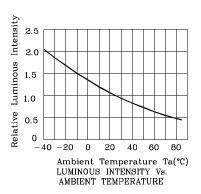


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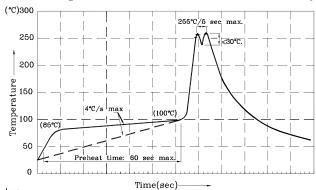








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2. Peak wave soldering temperature between $245^{\circ}C \sim 255^{\circ}C$ for 3 sec
- (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above $85\,^{\circ}\text{C}.$ 4.Fixtures should not incur stress on the component when mounting and
- during soldering process. 5.SAC 305 solder alloy is recommended.
- 6. No more than one wave soldering pass

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

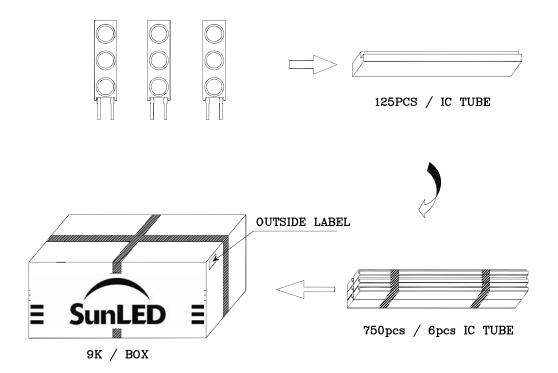
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

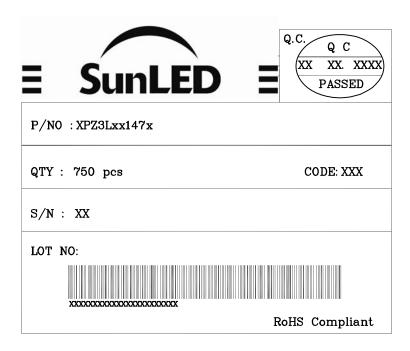
Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS





TERMS OF USE

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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- $6. \ Additional\ technical\ notes\ are\ available\ at\ \underline{http://www.SunLEDusa.com/TechnicalNotes.asp}$

Dec 28,2013